



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



## MM74C908 Dual CMOS 30-Volt Relay Driver

### General Description

The MM74C908 is a general purpose dual high voltage driver capable of sourcing a minimum of 250 mA at  $V_{OUT} = V_{CC} - 3V$ , and  $T_J = 65^\circ C$ .

The MM74C908 consists of two CMOS NAND gates driving an emitter follower Darlington output to achieve high current drive and high voltage capabilities. In the "OFF" state the outputs can withstand a maximum of  $-30V$  across the device. These CMOS drivers are useful in interfacing

normal CMOS voltage levels to driving relays, regulators, lamps, etc.

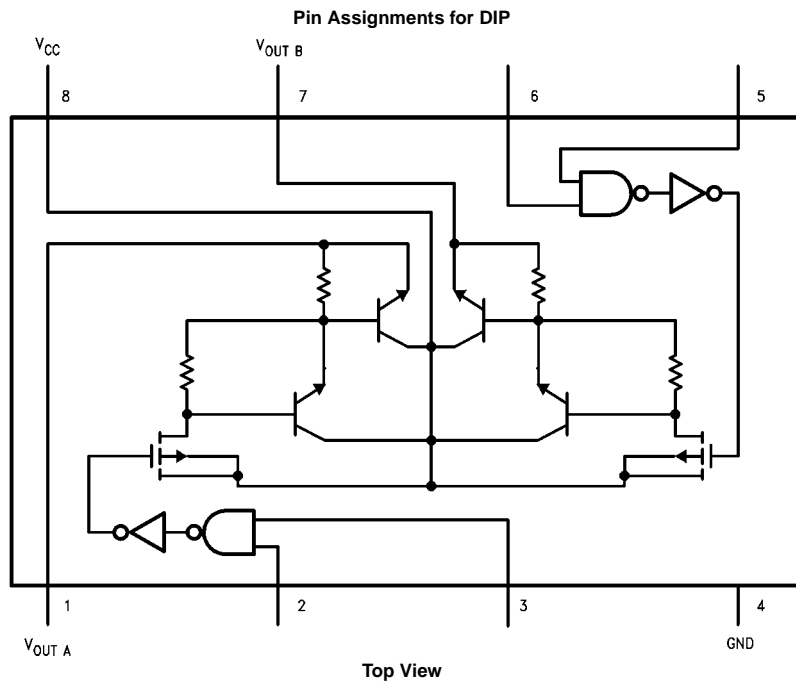
### Features

- Wide supply voltage range: 3V to 18V
- High noise immunity:  $0.45 V_{CC}$  (typ.)
- Low output "ON" resistance:  $8\Omega$  (typ.)
- High voltage:  $-30V$
- High current: 250 mA

### Ordering Code:

Order Number	Package Number	Package Description
MM74C908N	N08E	8-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

### Connection Diagram



Absolute Maximum Ratings (Note 1)		Lead Temperature ( $T_L$ )	260°C
Voltage at any Input Pin	-0.3V to $V_{CC} + 0.3V$	(Soldering, 10 seconds)	
Voltage at any Output Pin	32V	Power Dissipation ( $P_D$ )	Refer to Maximum Power Dissipation vs Ambient Temperature Graph
Operating Temperature Range	-40°C to +85°C		
Operating $V_{CC}$ Range	4V to 18V		
Absolute Maximum $V_{CC}$	19V		
$I_{SOURCE}$	500 mA		
Storage Temperature Range ( $T_S$ )	+150°C		
	-65°C to +150°C		

**Note 1:** "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. Except for "Operating Temperature Range" they are not meant to imply that the devices should be operated at these limits. The Electrical Characteristics table provides conditions for actual device operation.

## DC Electrical Characteristics

Min/Max limits apply across temperature range, unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>CMOS TO CMOS</b>						
$V_{IN(1)}$	Logical "1" Input Voltage	$V_{CC} = 5V$	3.5			V
		$V_{CC} = 10V$	8.0			V
$V_{IN(0)}$	Logical "0" Input Voltage	$V_{CC} = 5V$			1.5	V
		$V_{CC} = 10V$			2.0	V
$I_{IN(1)}$	Logical "1" Input Current	$V_{CC} = 15V, V_{IN} = 15V$		0.005	1.0	$\mu A$
$I_{IN(0)}$	Logical "0" Input Current	$V_{CC} = 15V, V_{IN} = 0V$	-1.0	-0.005		$\mu A$
$I_{CC}$	Supply Current	$V_{CC} = 15V$ , Outputs Open Circuit		0.05	15	$\mu A$
	Output "OFF" Voltage	$V_{IN} = V_{CC}, I_{OUT} = -200 \mu A$		-30		V
<b>CMOS/LPTTL INTERFACE</b>						
$V_{IN(1)}$	Logical "1" Input Voltage	$V_{CC} = 4.75V$	$V_{CC} - 1.5$			V
$V_{IN(0)}$	Logical "0" Input Voltage	$V_{CC} = 4.75V$			0.8	V
<b>OUTPUT DRIVE</b>						
$V_{OUT}$	Output Voltage	$I_{OUT} = -300 \text{ mA}, V_{CC} \geq 5V, T_J = 25^\circ C$	$V_{CC} - 2.7$	$V_{CC} - 1.8$		V
		$I_{OUT} = -250 \text{ mA}, V_{CC} \geq 5V, T_J = 65^\circ C$	$V_{CC} - 3.0$	$V_{CC} - 1.9$		V
		$I_{OUT} = -175 \text{ mA}, V_{CC} \geq 5V, T_J = 150^\circ C$	$V_{CC} - 3.15$	$V_{CC} - 2.0$		V
$R_{ON}$	Output Resistance	$I_{OUT} = -300 \text{ mA}, V_{CC} \geq 5V, T_J = 25^\circ C$		6.0	9.0	$\Omega$
		$I_{OUT} = -250 \text{ mA}, V_{CC} \geq 5V, T_J = 65^\circ C$		7.5	12	$\Omega$
		$I_{OUT} = -175 \text{ mA}, V_{CC} \geq 5V, T_J = 150^\circ C$		10	18	$\Omega$
	Output Resistance Coefficient			0.55	0.80	%/ $^\circ C$
$\theta_{JA}$	Thermal Resistance	(Note 2)		100	110	$^\circ C/W$
	MM74C908	(Note 2)		45	55	$^\circ C/W$

**Note 2:**  $\theta_{JA}$  measured in free air with device soldered into printed circuit board.

## AC Electrical Characteristics (Note 3)

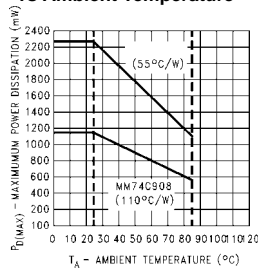
Symbol	Parameter	Conditions	Min	Typ	Max	Units
$t_{pd1}$	Propagation Delay to a Logical "1"	$V_{CC} = 5V, R_L = 50\Omega, C_L = 50 \text{ pF}, T_A = 25^\circ C$		150	300	ns
		$V_{CC} = 10V, R_L = 50\Omega, C_L = 50 \text{ pF}, T_A = 25^\circ C$		65	120	ns
$t_{pd0}$	Propagation Delay to a Logic "0"	$V_{CC} = 5V, R_L = 50\Omega, C_L = 50 \text{ pF}, T_A = 25^\circ C$		2.0	10	$\mu s$
		$V_{CC} = 10V, R_L = 50\Omega, C_L = 50 \text{ pF}, T_A = 25^\circ C$		4.0	20	$\mu s$
$C_{IN}$	Input Capacitance	(Note 4)		5.0		pF

**Note 3:** AC Parameters are guaranteed by DC correlated testing.

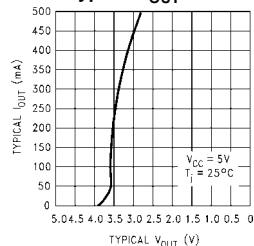
**Note 4:** Capacitance is guaranteed by periodic testing.

## Typical Performance Characteristics

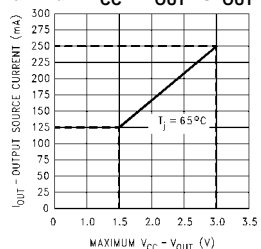
Maximum Power Dissipation vs Ambient Temperature



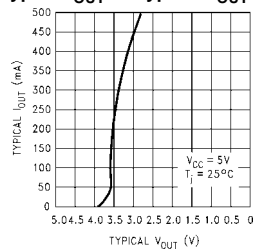
Typical I<sub>OUT</sub> vs Typical V<sub>OUT</sub>



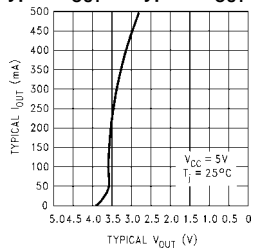
Maximum V<sub>CC</sub> - V<sub>OUT</sub> vs I<sub>OUT</sub>



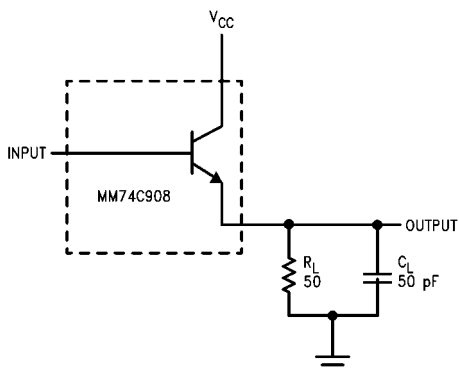
Typical I<sub>OUT</sub> vs Typical V<sub>OUT</sub>



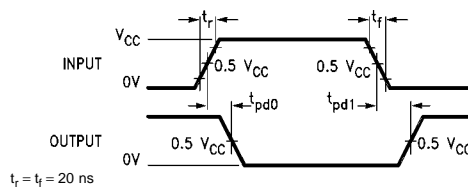
Typical I<sub>OUT</sub> vs Typical V<sub>OUT</sub>



## AC Test Circuit



## Switching Time Waveforms



## Power Considerations

### Calculating Output "ON" Resistance ( $R_L > 18\Omega$ )

The output "ON" resistance,  $R_{ON}$ , is a function of the junction temperature,  $T_J$ , and is given by:

$$R_{ON} = 9 (T_J - 25) (0.008) + 9 \quad (1)$$

and  $T_J$  is given by:

$$T_J = T_A + P_{DAV} \theta_{JA} \quad (2)$$

where  $T_A$  = ambient temperature,  $\theta_{JA}$  = thermal resistance, and  $P_{DAV}$  is the average power dissipated within the device.  $P_{DAV}$  consists of normal CMOS power terms (due to leakage currents, internal capacitance, switching, etc.) which are insignificant when compared to the power dissipated in the outputs. Thus, the output power term defines the allowable limits of operation and includes both outputs, A and B.  $P_D$  is given by:

$$P_D = I_{OA}^2 R_{ON} + I_{OB}^2 R_{ON} \quad (3)$$

where  $I_O$  is the output current, given by:

$$I_O = \frac{V_{CC} - V_L}{R_{ON} + R_L} \quad (4)$$

$V_L$  is the load voltage.

The average power dissipation,  $P_{DAV}$ , is a function of the duty cycle:

$$P_{DAV} = I_{OA}^2 R_{ON} (\text{Duty Cycle}_A) + I_{OB}^2 R_{ON} (\text{Duty Cycle}_B) \quad (5)$$

where the duty cycle is the % time in the current source state. Substituting equations (1) and (5) into (2) yields:

$$T_J = T_A + \theta_{JA} [9 (T_J - 25) (0.008) + 9] \quad (6a)$$

$$[I_{OA}^2 (\text{Duty Cycle}_A) + I_{OB}^2 (\text{Duty Cycle}_B)]$$

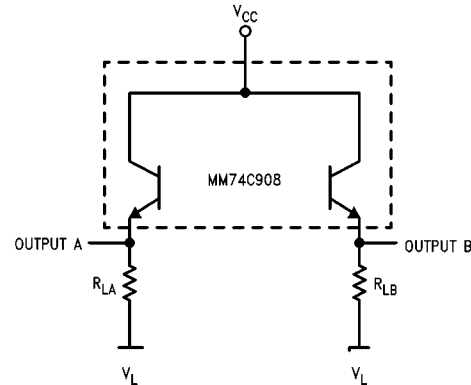
simplifying:

$$T_J = \frac{T_A + 7.2 \theta_{JA} [I_{OA}^2 (\text{Duty Cycle}_A) + I_{OB}^2 (\text{Duty Cycle}_B)]}{1 - 0.072 \theta_{JA} [I_{OA}^2 (\text{Duty Cycle}_A) + I_{OB}^2 (\text{Duty Cycle}_B)]}$$

## Applications

(See AN-177 for applications)

Equations (1), (4), and (6b) can be used in an iterative method to determine the output current, output resistance and junction temperature.



For example, let  $V_{CC} = 15V$ ,  $R_{LA} = 100\Omega$ ,  $R_{LB} = 100\Omega$ ,  $V_L = 0V$ ,  $T_A = 25^\circ C$ ,  $\theta_{JA} = 110^\circ C/W$ ,  $\text{Duty Cycle}_A = 50\%$ ,  $\text{Duty Cycle}_B = 75\%$ .

Assuming  $R_{ON} = 11\Omega$ , then:

$$I_{OA} = \frac{V_{CC} - V_L}{R_{ON} + R_{LA}} = \frac{15}{11 + 100} = 135.1 \text{ mA}$$

$$I_{OB} = \frac{V_{CC} - V_L}{R_{ON} + R_{LB}} = 135.1 \text{ mA}$$

and

$$T_J = \frac{T_A + 7.2 \theta_{JA} [I_{OA}^2 (\text{Duty Cycle}_A) + I_{OB}^2 (\text{Duty Cycle}_B)]}{1 - 0.072 \theta_{JA} [I_{OA}^2 (\text{Duty Cycle}_A) + I_{OB}^2 (\text{Duty Cycle}_B)]}$$

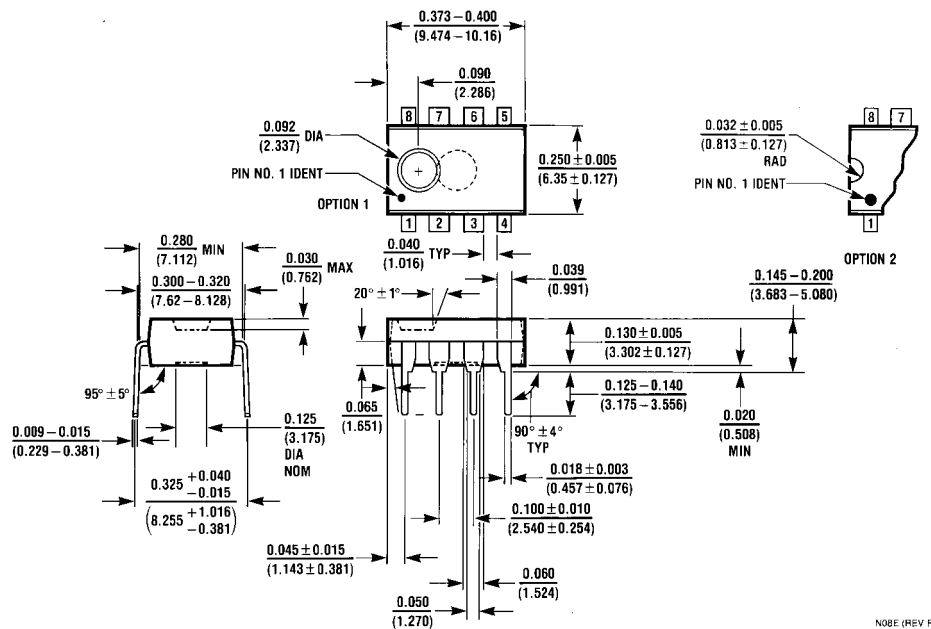
$$T_J = \frac{25 + (7.2) (110) [(0.1351)^2 (0.5) + (0.1351)^2 (0.75)]}{1 - (0.072) (110) [(0.1351)^2 (0.5) + (0.1351)^2 (0.75)]}$$

$$T_J = 52.6^\circ C$$

$$\text{and } R_{ON} = 9 (T_J - 25) (0.008) + 9$$

$$= 9(52.6 - 25) (0.008) + 9 = 11\Omega$$

**Physical Dimensions** inches (millimeters) unless otherwise noted



**8-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide  
Package Number N08E**

**LIFE SUPPORT POLICY**

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

[www.fairchildsemi.com](http://www.fairchildsemi.com)